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November 2010

FDD6N50TM_F085

500V N-Channel MOSFET

Features

- 6A, 500V, $R_{DS(on)} = 0.9\Omega$ @ $V_{GS} = 10 \text{ V}$
- Low gate charge (typical 12.8 nC)
- Low C_{rss} (typical 9 pF)
- · Fast switching
- · 100% avalanche tested
- · Improved dv/dt capability
- · Qualified to AEC Q101
- · RoHS Compliant

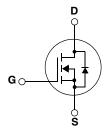
Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switched mode power supplies and active power factor correction.







Absolute Maximum Ratings

Symbol	Parameter		Ratings	Unit	
V _{DSS}	Drain-Source Voltage		500	V	
I _D	$ \begin{array}{ccc} \text{Drain Current} & & -\text{Continuous } (T_C = 25^{\circ}\text{C}) \\ & -\text{Continuous } (T_C = 100^{\circ}\text{C}) \end{array} $	` ` ` ` ` ` ` ` ` ` ` ` ` ` ` ` ` ` ` `		A A	
I _{DM}	Drain Current - Pulsed	(Note 1)	24	A	
V _{GSS}	Gate-Source voltage		±30	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	270	mJ	
I _{AR}	Avalanche Current	(Note 1)	6	A	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	8.9	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns	
P _D	Power Dissipation (T _C = 25°C) - Derate above 25°C		89 0.71	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
TL	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	Min.	Max.	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.4	°C/W	
$R_{\theta JA}$	$R_{ heta JA}$ Thermal Resistance, Junction-to-Ambient		83	°C/W	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD6N50	FDD6N50TM_F085	D-PAK	380mm	16mm	2500

Electrical Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Conditions	Min.	Тур.	Max	Units
Off Charac	teristics		I			
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA	500			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C		0.5		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 500V, V _{GS} = 0V V _{DS} = 400V, T _C = 125°C			1 10	μ Α μ Α
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30V, V _{DS} = 0V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30V, V _{DS} = 0V			-100	nA
On Charac	teristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 3A		0.76	0.9	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 40V, I_{D} = 3A$ (Note 4)		2.5		S
Dynamic C	Characteristics					
C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0V,		720	940	pF
C _{oss}	Output Capacitance	f = 1.0MHz		95	190	pF
C _{rss}	Reverse Transfer Capacitance			9	13.5	pF
Switching	Characteristics					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 250V, I_{D} = 6A$		6	20	ns
t _r	Turn-On Rise Time	$R_G = 25\Omega$		55	120	ns
$t_{d(off)}$	Turn-Off Delay Time			25	60	ns
t _f	Turn-Off Fall Time	(Note 4, 5)		35	80	ns
Q_g	Total Gate Charge	V _{DS} = 400V, I _D = 6A		12.8	16.6	nC
Q_{gs}	Gate-Source Charge	V _{GS} = 10V		3.7		nC
Q_{gd}	Gate-Drain Charge	(Note 4, 5)		5.8		nC
Drain-Sour	rce Diode Characteristics and Maximur	n Ratings	ı			•
I _S	Maximum Continuous Drain-Source Dio	de Forward Current			6	Α
I _{SM}	Maximum Pulsed Drain-Source Diode F	orward Current			24	Α
V_{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0V, I _S = 6A			1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 6A		275		ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$ (Note 4)		1.7		μС

NOTES:

 $^{{\}it 1. Repetitive Rating: Pulse width \ limited \ by \ maximum \ junction \ temperature}$

^{2.} I $_{AS}$ = 6A, V $_{DD}$ = 50V, L=13.5mH, R $_{G}$ = 25 Ω , Starting T $_{J}$ = 25 $^{\circ}$ C

^{3.} I $_{SD}$ \leq 6A, di/dt \leq 200A/µs, V $_{DD}$ \leq BV $_{DSS}$, Starting T $_{J}$ = 25°C

^{4.} Pulse Test: Pulse width $\leq 300 \mu \text{s}, \, \text{Duty Cycle} \leq 2\%$

^{5.} Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

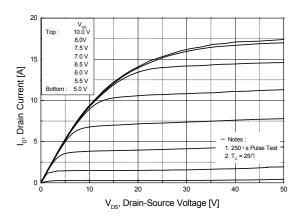


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

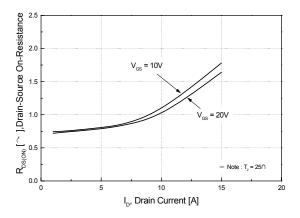


Figure 5. Capacitance Characteristics

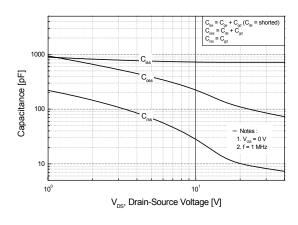


Figure 2. Transfer Characteristics

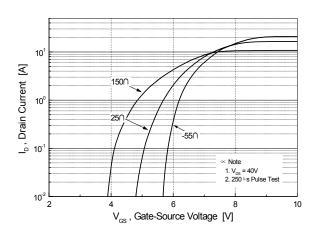


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

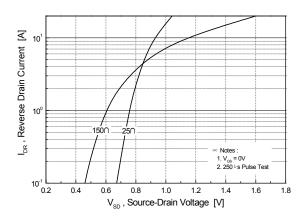
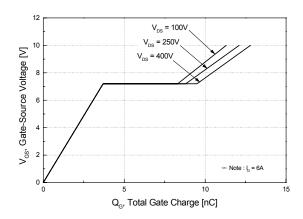


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

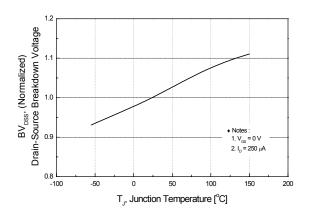


Figure 8. On-Resistance Variation vs. Temperature

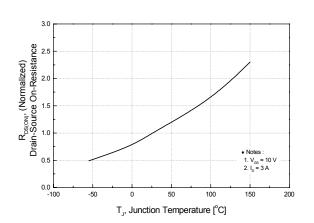


Figure 9. Maximum Safe Operating Area

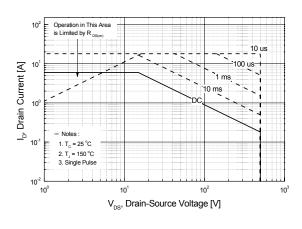


Figure 10. Maximum Drain Current vs. Case Temperature

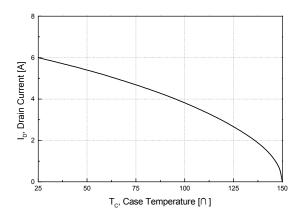
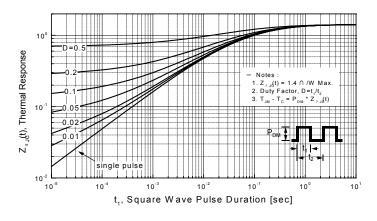
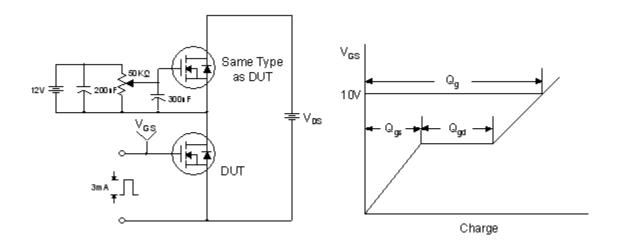


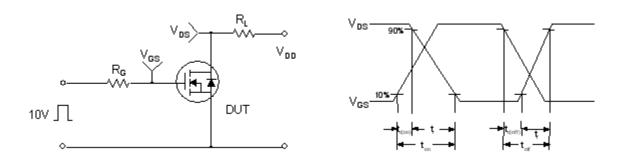
Figure 11. Transient Thermal Response Curve



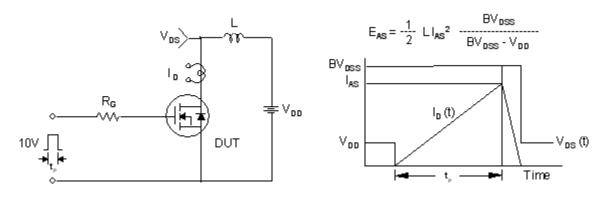
Gate Charge Test Circuit & Waveform



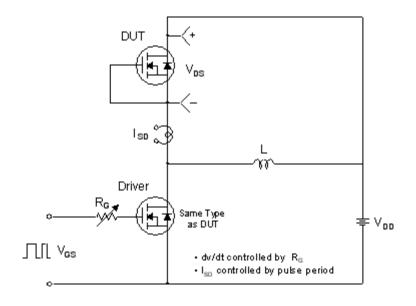
Resistive Switching Test Circuit & Waveforms

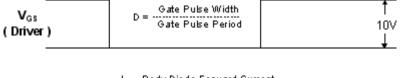


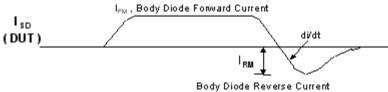
Unclamped Inductive Switching Test Circuit & Waveforms

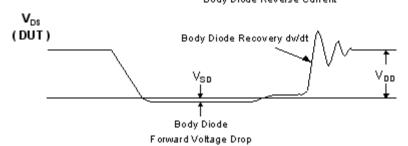


Peak Diode Recovery dv/dt Test Circuit & Waveforms



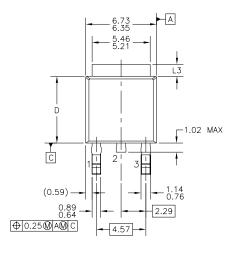


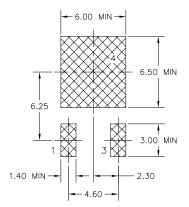




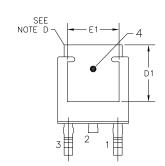
Mechanical Dimensions

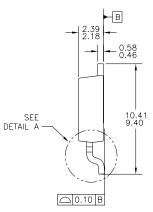
D-PAK

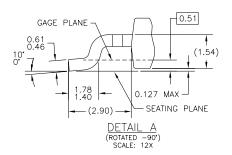




LAND PATTERN RECOMMENDATION







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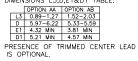
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